WAFER CHAMFERING METHOD AND APPARATUS

ABSTRACT OF THE DISCLOSURE

A wafer to be chamfered is supported in such a manner as to rotate and to move in the X-axis direction and the Y-axis direction which are perpendicular to one another, and a periphery grinding wheel is rotatably placed on the Y-axis. To chamfer a circular part of the wafer, the circular part of the wafer is pressed against the rotating periphery grinding wheel, and then, the wafer is rotated. To chamfer an orientation flat of the wafer, the orientation flat of the wafer is pressed against the rotating periphery grinding wheel, and then, the wafer is fed in the X-axis direction.

(Fig. 4)

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